

Title (en)

Contact assembly for electrically contacting a circuit board

Title (de)

Kontaktanordnung zum elektrischen Kontaktieren einer Leiterplatte

Title (fr)

Agencement de contact pour la mise en contact électrique d'une carte de circuit imprimé

Publication

EP 2693570 B1 20170426 (DE)

Application

EP 13177445 A 20130722

Priority

DE 102012213806 A 20120803

Abstract (en)

[origin: EP2693570A1] The arrangement (14) has contact elements (15) for electrically contacting a printed circuit board (PCB) (10). The contact elements include electrically conductive contact surfaces (18) for electrical contacting of a spring element of a plug. The contact surfaces are provided at oppositely lying surfaces of the PCB. The contact elements include spacer elements (16a), which are carried by the PCB and carry the contact surfaces, so that contact surfaces include a spacing to a surface of the PCB. The spacer elements are curved over a surface of the PCB.

IPC 8 full level

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CPC (source: EP)

H01R 12/57 (2013.01); **H01R 12/718** (2013.01); **H01R 13/24** (2013.01)

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